



CALL FOR PAPERS

IMPORTANT DATES

January 15, 2023

- Tutorial Proposal Submission Deadline
- Focused Session Proposal Submission Deadline

January 22, 2023

- Tutorial Proposal Submission Acceptance
- Focused Session Proposal Submission Acceptance

February 20, 2023

Initial Paper Submission Deadline

March 31, 2023

Notification of Acceptance

April 16, 2023

Final Manuscript Submission Deadline

June 10, 2023

Open Preview Publication Accessible
Through IEEE Xplore

June 16, 2023

Standard Registration Deadline



The IEEE International Conference on Flexible, Printable Sensors and Systems (FLEPS 2023) will be held in Boston, Massachusetts, USA.

IEEE FLEPS 2023 is intended to provide a forum for research scientists, engineers, and practitioners throughout the world to present their latest research findings, ideas, and applications in the area of Flexible and Printable Sensors and Systems.

TOPICS OF INTEREST

- » Organic/Inorganic Electronics and Sensors
- » Emerging Materials for Flexible and Printable Systems
- » Advanced Manufacturing Techniques
- » High-throughput Printable Electronics
- » Hybrid Flexible Sensors and Electronics
- » Stretchable/Shrinkable Sensors and Electronics
- » Soft/Smart Wearable and Implantable Sensing Systems
- » Disposable/Reusable Sensors and Electronics
- » Printed Large-Area Sensors and Systems
- » Active and Passive Components (e.g. actuators, printed energy devices, smart labels, RFID etc.)
- » Emerging applications of Flexible Electronics inc. IoT, smart cities etc.
- » Reliability, Simulation and Modelling
- » Flexible/Printable Electronics in context with Circular and Green Electronics

For further information, contact **Coral Miller** at Conference Catalysts, LLC.

